



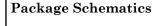


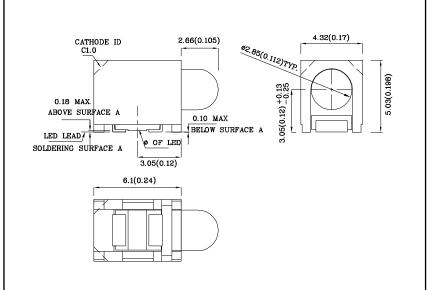
Features

- •Surface mount type
- •Compatible with automatic placement equipment
- •Compatible with infrared and vapor phase solder processes
- ullet Black case enhances contrast ratio
- Housing material meets UL94V-0 flammability rating
- •Lens material meets UL94-HB flammability rating
- •MSL (Moisture Sensitivity Level): 4
- $\bullet RoHS$ compliant









Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		VG (AlGaInP)	Unit	
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	150	mA	
Power Dissipation	P_D	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +100	C	

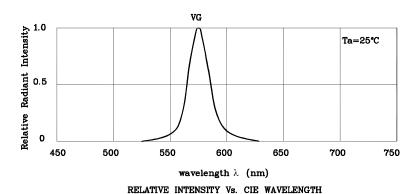
Operating Characteristics (T _A =25°C)		VG (AlGaInP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =10mA)	λP	574*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =10mA)	λD	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

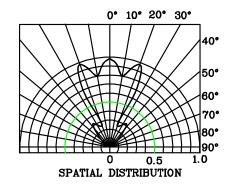
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} \text{Luminous Intensity} \\ \text{CIE127-2007*} \\ \text{(I}_{\text{F}}\text{=}10\text{mA}) \\ \text{mcd} \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XPR1ZVG45S	Green	AlGaInP	Water Clear	5*	14*	574*	50°

 $^{^*}$ Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

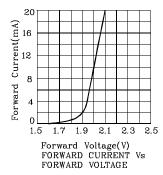


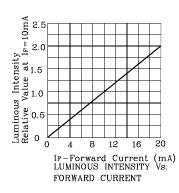


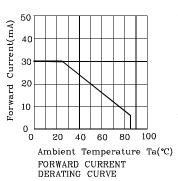


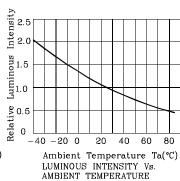


❖ VG



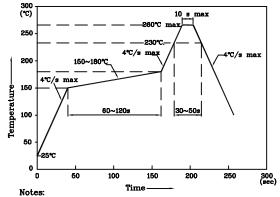






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

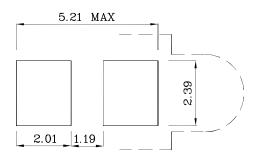


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

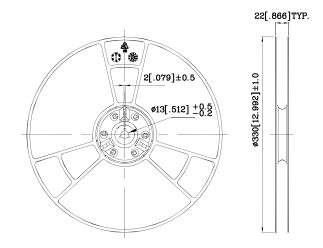




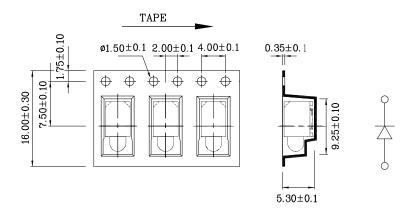
❖ Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

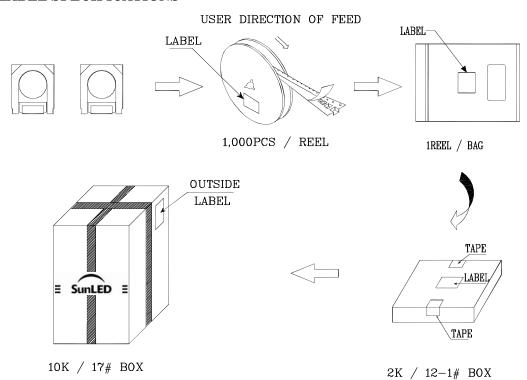
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

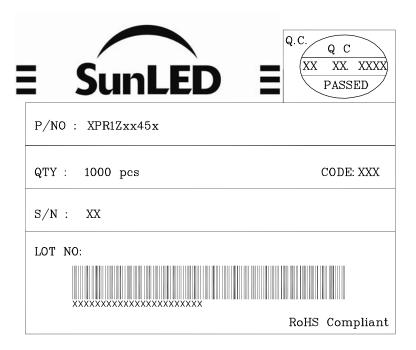
Note: Accuracy may depend on the sorting parameters.

May 23, 2014

SINGLE LEVEL SURFACE MOUNT CBI

PACKING & LABEL SPECIFICATIONS





TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

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XDSB7905 V1-Z Layout: Maggie L